

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A silicon platform for optical modules comprising:
a silicon substrate;
a first insulating layer formed on the silicon substrate;
a first conductor layer formed on the first insulating layer;
a second insulating layer formed on the first conductor layer; and
a second conductor layer formed on the second insulating layer, wherein
an end portion of the second conductor layer is in direct contact with ~~overlying~~ the
first insulating layer to constitute a bonding portion to be connected to a lead wires
wire.

Claim 2 (Currently Amended): A silicon platform for optical modules according to
claim 1, wherein a hole is formed in the second insulating layer and a the bonding portion is
formed in ~~this~~ the hole.

Claim 3 (Currently Amended): A silicon platform for optical modules according to
claim 1, wherein a ~~removed portion is formed~~ in the second insulating layer is removed and a
the bonding portion is formed in ~~this removed~~ the portion.

Claim 4 (Original): A silicon platform for optical modules according to claim 1,
wherein the second insulating layer has a thickness of 6 μm or less.

Claim 5 (Currently Amended): A silicon platform for optical modules according to
claim 1, wherein an optical ~~elements are~~ element is mounted on a conductor pattern formed

thereon and an end portion of the second conductor layer is connected to the conductor pattern through a connection conductor pattern ~~lies right below the optical elements.~~

Claim 6 (Currently Amended): A silicon platform for optical modules according to claim [[1]] 5, wherein a portion of the first insulating layer below the connection conductor pattern and the bonding portion is thicker than the other portion of the first insulating layer ~~a bulky portion is formed on part of the first insulating layer.~~

Claim 7 (Original): A silicon platform for optical modules according to claim 1, wherein the first conductor layer, the second insulating layer and the second conductor layer constitutes a microstrip line structure.

Claim 8 (Original): A silicon platform for optical modules according to claim 1, wherein the second conductor layer constitutes a coplanar distribution constant circuit structure.

Claim 9 (Original): A silicon platform for optical modules according to claim 1, which is electrically connected to a driver IC by lead wires.

Claim 10 (Original): A silicon platform for optical modules according to claim 1, wherein at least one of a light emitting element and a light-receiving element are mounted.

Claim 11 (Original): A silicon platform for optical modules according to claim 1, wherein the first insulating layer is an oxide layer.

Claim 12 (Original): A silicon platform for optical modules according to claim 1,
wherein the first insulating layer is an SiO₂ insulating layer.

Claim 13 (Original): A silicon platform for optical modules according to claim 1,
wherein the second insulating layer is a resin layer.

Claim 14 (Original): A silicon platform for optical modules according to claim 1,
wherein the second insulating layer is a polyimide layer.